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**Makabe et al.**

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(54) **SUBSTRATE TEMPERATURE ADJUSTING METHOD AND A METHOD OF CHANGING THE TEMPERATURE CONTROL RANGE OF A HEATER IN A SUBSTRATE PROCESSING APPARATUS**

(58) **Field of Classification Search**  
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See application file for complete search history.

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(\* ) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 580 days.

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(57) **ABSTRACT**

(51) **Int. Cl.**  
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A method which changes the temperature control range of a heater of a substrate processing apparatus. The temperature control range of a heater is changed or extended by changing the flow rate of the coolant flowing through a coolant channel from a first flow rate to a second flow rate which is smaller than the first flow rate, to change a first thermal conductivity of a mounting table to a second thermal conductivity which is smaller than the first thermal conductivity. The upper limit of the temperature control range is lower than the heat resistant temperature of a material of an adhesive of the mounting table.

(52) **U.S. Cl.**  
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**4 Claims, 14 Drawing Sheets**

